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## PATENT NUMBER and ISSUE DATE

## U.S. **UTILITY** Patent Application

AI N	APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER	
_	10021257	12/19/2001	-1604	· ,	2841		
	**APPLICANT	S: Chinda	Akira; Ma	itsuura Akira;			
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For	eign priority claimed		□ yes □	RESCIND			
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TIT	LE : Wiring boa	rd semiconductor	S		03	35532-0118	
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NOTICE OF ALLOWANCE MAILED  ISSUE FEE			CLAIMS ALLOWED					
		Assistant Examiner	Total Claims		Print Claim for O.G			
			DRAWING					
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.			
		Primary Examiner		<u> </u>	<u>L</u>			
TERMINAL		PREPARED FOR ISSUE	Application Examiner					
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